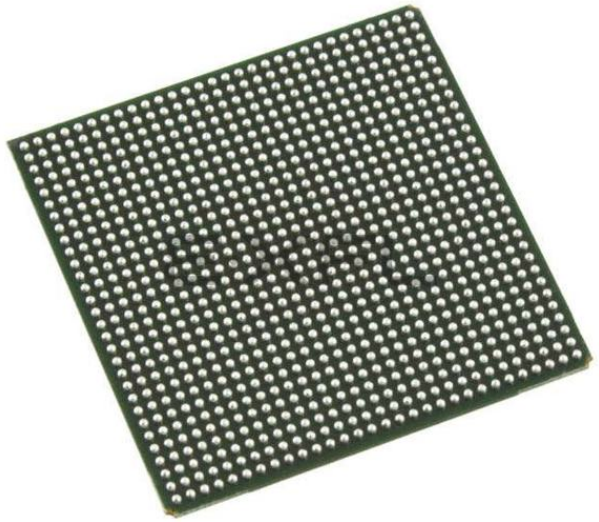
Lattice Semiconductor Corporation - LFSCM3GA15EP1-5FN900I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

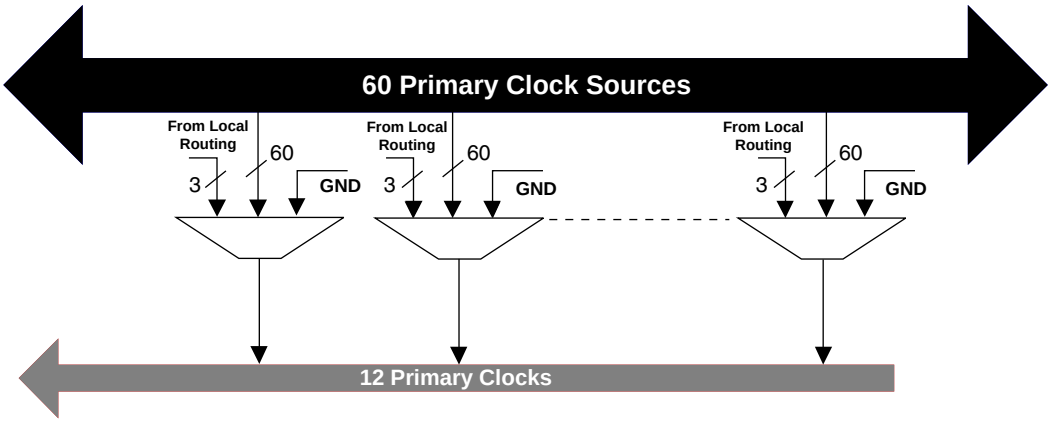
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3750
Number of Logic Elements/Cells	15000
Total RAM Bits	1054720
Number of I/O	300
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga15ep1-5fn900i

Figure 2-6. Per Quadrant Clock Selection



Note: GND is available to switch off the network.

Secondary Clocks

In addition to the primary clock network and edge clocks the LatticeSC devices also contain a secondary clock network. Built of X6 style routing elements this secondary clock network is ideal for routing slower speed clock and control signals throughout the device preserving high-speed clock networks for the most timing critical signals.

Edge Clocks

LatticeSC devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are eight edge clocks per bank for the top and bottom of the device. The left and right sides have eight edge clocks per side for both banks located on that side. Figure 2-7 shows the arrangement of edge clocks.

Edge clock resources can be driven from a variety of sources. Edge clock resources can be driven from:

- Edge clock PIOs in the same bank
- Primary clock PIOs in the same bank
- Routing
- Adjacent PLLs and DLLs
- ELSR output from the clock divider

Table 2-10. Supported Output Standards[4]

Output Standard	Drive	V_{CCIO} (Nom)	On-chip Output Termination
Single-ended Interfaces			
LVTTL/D[1]	8mA, 16mA, 24mA	3.3	None.
LVCMOS33/D[1]	8mA, 16mA, 24mA	3.3	None
LVCMOS25/D[1, 2]	4mA, 8mA, 12mA, 16mA,	2.5	None, series: 25, 33, 50, 100
LVCMOS18/D[1, 2]	4mA, 8mA, 12mA, 16mA,	1.8	None, series: 25, 33, 50, 100
LVCMOS15/D[1, 2]	4mA, 8mA, 12mA, 16mA,	1.5	None, series: 25, 33, 50, 100
LVCMOS12/D[1, 2]	2mA, 4mA, 8mA, 12mA	1.2	None, series: 25, 33, 50, 100
PCIX15	N/A	1.5	None
PCI33, PCIX33, AGP1X33, AGP2X33	N/A	3.3	None
HSTL18_I	N/A	1.8	None, series: 50
HSTL18_II	N/A	1.8	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
HSTL15_I	N/A	1.5	None, series: 50
HSTL15_II	N/A	1.5	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
SSTL33_I	N/A	3.3	None
SSTL33_II	N/A	3.3	None
SSTL25_I	N/A	2.5	None, series: 50
SSTL25_II	N/A	2.5	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
SSTL18_ I	N/A	1.8	None, series: 33
SSTL18_II	N/A	1.8	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
Differential Interfaces			
SSTL18D_I	N/A	1.8	None, series: 33
SSTL25D_I	N/A	2.5	None, series: 50
SSTL18D_II, SSTL25D_II	N/A	1.2/2.5/3.3	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
SSTL33D_I, II	N/A	3.3	None
HSTL15D_I, HSTL18D_I	N/A	1.5/1.8	None, series: 50
HST15D_II, HSTL18D_II	N/A	1.5/1.8	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
LVDS	2mA, 3.5mA, 4mA, 6mA	N/A	None
Mini-LVDS	3.5mA, 4mA, 6mA	N/A	None
BLVDS25	N/A	N/A	None
MLVDS25	N/A	N/A	None
LVPECL33[3]	N/A	3.3	None
RSDS	2mA, 3.5mA, 4mA, 6mA	N/A	None

1. D refers to open drain capability.
2. User can select either drive current or driver impedances but not both.
3. Emulated with external resistors.
4. No GTL or GTL+ support.

PCI Clamp

A programmable PCI clamp is available on the top and bottom banks of the device. The PCI clamp can be turned “ON” or “OFF” on each pin independently. The PCI clamp is used when implementing a 3.3V PCI interface. The

PCI Specification, Revision 2.2 requires the use of clamping diodes for 3.3V operation. For more information on the PCI interface, please refer to the PCI Specification, Revision 2.2.

Programmable Slew Rate Control

All output and bidirectional buffers have an optional programmable output slew rate control that can be configured for either low noise or high-speed performance. Each I/O pin has an individual slew rate control. This allows designers to specify slew rate control on a pin-by-pin basis. This slew rate control affects both the rising and falling edges.

Programmable Termination

Many of the I/O standards supported by the LatticeSC devices require termination at the transmitter, receiver or both. The SC devices provide the capability to implement many kinds of termination on-chip, minimizing stub lengths and hence improving performance. Utilizing this feature also has the benefit of reducing the number of discrete components required on the circuit board. The termination schemes can be split into two categories single-ended and differential.

Single Ended Termination

Single Ended Outputs: The SC devices support a number of different terminations for single ended outputs:

- Series
- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to $V_{CCIO}/2$ combined with series

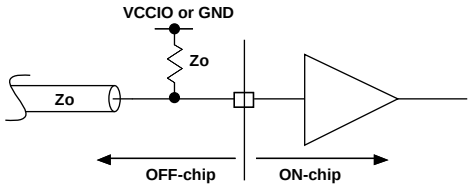
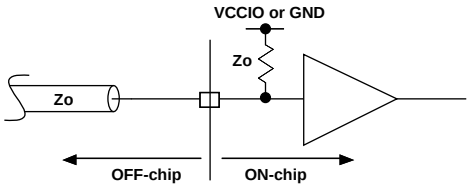
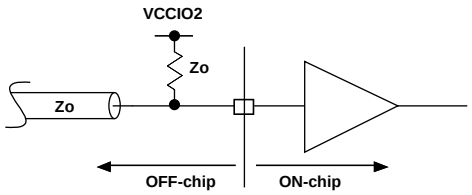
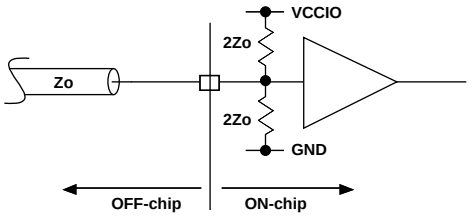
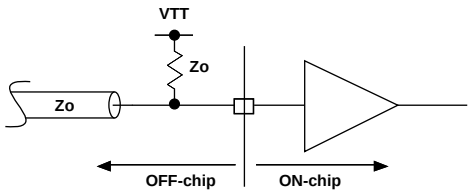
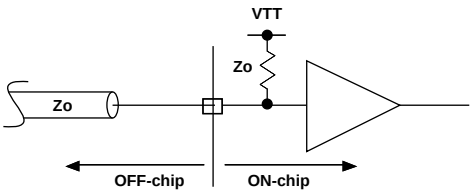
Figure 2-27 shows the single ended output schemes that are supported. The nominal values of the termination resistors are shown in Table 2-10.

Single Ended Inputs: The SC devices support a number of different termination schemes for single ended inputs:

- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to V_{TT}

Figure 2-28 shows the single ended input schemes that are supported. The nominal values of the termination resistors are shown in Table 2-9.

Figure 2-28. Input Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Parallel termination to to V_{CCIO}, or parallel to GND receiving end		
Parallel termination to $V_{CCIO}/2$ receiving end		
Parallel termination to V_{TT} at receiving end		

In many situations designers can chose whether to use Thevenin or parallel to V_{TT} termination. The Thevenin approach has the benefit of not requiring a termination voltage to be applied to the device. The parallel to V_{TT} approach consumes less power.

VTT Termination Resources

Each I/O bank, except bank 1, has a number of V_{TT} pins that must be connected if V_{TT} is used. Note V_{TT} pins can sink or source current and the power supply they are connected to must be able to handle the relatively high currents associated with the termination circuits. Note: V_{TT} is not available in all package styles.

On-chip parallel termination to V_{TT} is supported at the receiving end only. On-chip parallel output termination to V_{TT} is not supported.

The V_{TT} internal bus is also connected to the internal V_{CMT} node. Thus in one bank designers can implement either V_{TT} termination or V_{CMT} termination for differential inputs.

DDRII/RLDRAMII Termination Support

The DDR II memory and RLDRAMII (in Bidirection Data mode) standards require that the on-chip termination to V_{TT} be turned on when a pin is an input and off when the pin is an output. The LatticeSC devices contain the required circuitry to support this behavior. For additional detail refer to technical information at the end of the data sheet.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:
VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:
If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supples and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply
All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

LatticeSC/M External Switching Characteristics[3]

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (using Primary Clock without PLL)[2]								
t_{CO}	Global Clock Input to Output - PIO Output Register	2.83	5.74	2.83	6.11	2.83	6.49	ns
t_{SU}	Global Clock Input Setup - PIO Input Register without fixed input delay	-0.66	—	-0.66	—	-0.66	—	ns
t_{H}	Global Clock Input Hold - PIO Input Register without fixed input delay	1.73	—	1.95	—	2.16	—	ns
t_{SU_IDLY}	Global Clock Input Setup - PIO Input Register with input delay	0.86	—	1.03	—	1.20	—	ns
t_{H_IDLY}	Global Clock Input Hold - PIO Input Register with input delay	-0.17	—	-0.17	—	-0.17	—	ns
f_{MAX_PFU}	Global Clock frequency of PFU register	—	700	—	700	—	700	MHz
f_{MAX_IO}	Global Clock frequency of I/O register	—	1000	—	1000	—	1000	MHz
t_{GC_SKEW}	Global Clock skew	—	89	—	103	—	116	ps
General I/O Pin Parameters (using Primary Clock with PLL)[1, 2]								
t_{CO}	Global Clock Input to Output - PIO Output Register	2.25	4.81	2.25	5.08	2.25	5.37	ns
t_{SU}	Global Clock Input Setup - PIO Input Register without fixed input delay	-0.07	—	-0.07	—	-0.07	—	ns
t_{H}	Global Clock Input Hold - PIO Input Register without fixed input delay	0.80	—	0.93	—	1.04	—	ns
General I/O Pin Parameters (using Edge Clock without PLL)[2]								
t_{CO}	Edge Clock Input to Output - PIO Output Register	2.38	4.77	2.38	5.04	2.38	5.33	ns
t_{SU}	Edge Clock Input Setup - PIO Input Register without fixed input delay	-0.08	—	-0.08	—	-0.08	—	ns
t_{H}	Edge Clock Input Hold - PIO Input Register	0.49	—	0.58	—	0.66	—	ns
t_{SU_IDLY}	Edge Clock Input Setup - PIO Input Register with input delay	0.81	—	0.97	—	1.12	—	ns
t_{H_IDLY}	Edge Clock Input Hold - PIO Input Register with input delay	-0.34	—	-0.34	—	-0.34	—	ns
t_{EC_SKEW}	Edge Clock skew	—	28	—	32	—	36	ps
General I/O Pin Parameters (using Latch FF without PLL)[2]								
t_{SU}	Latch FF, Input Setup - PIO Input Register without fixed input delay	-0.14	—	-0.14	—	-0.14	—	ns
t_{H}	Latch FF, Input Hold - PIO Input Register without fixed input delay	0.58	—	0.68	—	0.77	—	ns
t_{SU_IDLY}	Latch FF, Input Setup - PIO Input Register with input delay	0.70	—	0.68	—	0.77	—	ns
t_{H_IDLY}	Latch FF, Input Hold - PIO Input Register with input delay	-0.30	—	-0.30	—	-0.30	—	ns

1. No PLL delay tuning (clock injection removal mode, system clock feedback).
2. Using LVCMOS25 12mA I/O. Timing adders for other supported I/O technologies are specified in the LatticeSC Family Timing Adders table.
3. Complete Timing Parameters for a user design are incorporated when running ispLEVER. This is a sampling of the key timing parameters. Timing specs are for non-AIL applications.

LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
GTLPLUS15	GTLPLUS15	-0.013	-0.017	0.012	0.004	0.037	0.024	ns
GTL12	GTL12	-0.063	-0.071	-0.007	-0.048	0.056	-0.032	ns
Output Adjusters								
LVDS	LVDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
RSDS	RSDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
BLVDS25	BLVDS	-0.129	0.05	-0.136	0.069	-0.136	0.083	ns
MLVDS25	MLVDS	-0.059	0.059	-0.057	0.096	-0.054	0.133	ns
LVPECL33	LVPECL	-0.334	-0.181	-0.325	-1.389	-0.315	-2.598	ns
HSTL18_I	HSTL_18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18_II	HSTL_18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL18D_I	Differential HSTL 18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18D_II	Differential HSTL 18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL15_I	HSTL_15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15_II	HSTL_15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
HSTL15D_I	Differential HSTL 15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15D_II	Differential HSTL 15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
SSTL33_I	SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33_II	SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL33D_I	Differential SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33D_II	Differential SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL25_I	SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25_II	SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL25D_I	Differential SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25D_II	Differential SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL18_I	SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18_II	SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
SSTL18D_I	Differential SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18D_II	Differential SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
LVTTL33_8mA	LVTTL 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVTTL33_16mA	LVTTL 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVTTL33_24mA	LVTTL 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVCMOS33_24mA	LVCMOS 3.3 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	-0.174	0.004	-0.195	0.002	-0.215	0	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0	0	0	0	0	0	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.094	-0.025	0.107	0.096	0.12	0.216	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.145	-0.054	0.162	0.063	0.181	0.179	ns
LVCMOS25_OD	LVCMOS 2.5 open drain	0.073	-0.125	0.081	-0.081	0.091	-0.09	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	-0.278	-0.099	-0.312	-0.115	-0.345	-0.131	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	-0.073	-0.078	-0.078	-0.084	-0.083	-0.089	ns

Signal Descriptions (Cont.)

Signal Name	I/O	Description
PROBE_GND	—	GND signal - Connected to internal VSS node. Can be used for feedback to control an external board power converter. Can be unconnected if not used.
PLL and Clock Functions (Used as user-programmable I/O pins when not in use for PLL, DLL or clock pins.)		
[LOC]_PLL[T, C]_FB_[A/B]	I	PLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T, C] indicates whether input is true or complement. [A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_FB_[C, D, E, F]	I	DLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners.
[LOC]_PLL[T, C]_IN[A/B]	I	PLL reference clock input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T, C] indicates whether input is true or complement.[A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_IN[C, D, E, F]		DLL reference clock inputs. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners. PCKLxy_[0:3] can drive primary clocks, edge clocks, and CLKDIVs. PCLKxy_[4:7] can only drive edge clocks.
PCLKxy_z		General clock inputs. x indicates whether T (true) or C (complement). y indicates the I/O bank the clock is associated with. z indicates the clock number within a bank.
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
Configuration Pads (Dedicated pins. Used during sysCONFIG.)		
M[3:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled that will pull the I/O above 1.5V.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESP_[ULC/URC]	—	Calibration resistor to be placed between this pin and either ground or RESPN_[ULC/URC]. RESPN_[ULC/URC] is available on select packages. If available, connection of calibration resistor between RESP_[ULC/URC] and RESPN_[ULC/URC] takes precedence over connection of calibration resistor between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
RESPN_[ULC/URC]	—	Available on selected packages. If available, calibration resistor should be placed between RESP_[ULC/URC] and RESPN_[ULC/URC] instead of between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
[A:D]_VDDIBx_[L/R]	—	Input buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDOBx_[L/R]	—	Output buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDAX25_[L/R]	—	Auxiliary power for input and output termination (2.5V) on left [L] or right [R] side of device.

1. The ispLEVER software tools may specify VDDRX, VDDTX, VDDP and VCCL pins. These pins should be considered VCC12 pins.
Note: Signals listed as Signal A / Signal B define the same physical pin that is used for different functions based on configuration mode.

Pin Information Summary

Pin Type		256 fpBGA	900 fpBGA		1020 fcBGA	
		LFSC/M15	LFSC/M15	LFSC/M25	LFSC/M25	LFSC/M40
Single Ended User I/O		139	300	378	476	562
Differential Pair User I/O		60	141	182	235	277
LVDS Output Pairs		22	44	60	60	78
Configuration	Dedicated	9	11	11	11	11
	Muxes/MPI sysBus	0	55	55	55	72
JTAG (excluding VCCJ)		4	4	4	4	4
Dedicated Pins		2	4	4	4	4
VCC		10	46	46	40	40
VCC12		10	35	35	36	36
VCCAUX		10	36	36	32	32
VCCIO	Bank 1	3	18	18	10	10
	Bank 2	2	14	14	8	8
	Bank 3	2	15	15	10	10
	Bank 4	3	15	15	10	10
	Bank 5	3	15	15	10	10
	Bank 6	2	15	15	10	10
	Bank 7	2	16	16	8	8
VTT	Bank 2	0	2	2	2	2
	Bank 3	0	3	3	3	3
	Bank 4	0	3	3	3	3
	Bank 5	0	3	3	3	3
	Bank 6	0	3	3	3	3
	Bank 7	0	2	2	2	2
GND		26	177	177	134	134
NC		0	102	24	92	6
Single Ended User / Differential I/O per Bank	Bank 1	21/8	63/30	63/30	68/32	68/32
	Bank 2	15/7	26/13	30/15	34/17	54/27
	Bank 3	19/8	43/20	62/29	84/42	94/47
	Bank 4	25/11	50/22	66/32	84/41	99/48
	Bank 5	25/11	49/23	65/32	88/44	99/49
	Bank 6	19/8	43/20	62/29	84/42	94/47
	Bank 7	15/7	26/13	30/15	34/17	54/27
LVDS Output Pairs Per Bank	Bank 2	5	7	9	9	15
	Bank 3	6	15	21	21	24
	Bank 6	6	15	21	21	24
	Bank 7	5	7	9	9	15
VCCJ		1	1	1	1	1
SERDES (signal + power supply)		28	60	60	108	108
Total		256	900	900	1020	1152

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AM21	PB29A	5		PB38A	5	
AM20	PB29B	5		PB38B	5	
AH21	PB29C	5		PB38C	5	
AH20	PB29D	5		PB38D	5	
AJ18	PB31A	5		PB39A	5	
AK18	PB31B	5		PB39B	5	
AH19	PB31C	5		PB39C	5	
AH18	PB31D	5		PB39D	5	
AL19	PB32A	5		PB41A	5	
AM19	PB32B	5		PB41B	5	
AH17	PB32C	5		PB41C	5	
AG17	PB32D	5		PB41D	5	
AL18	PB33A	5		PB42A	5	
AM18	PB33B	5		PB42B	5	
AC17	PB33C	5		PB42C	5	
AD17	PB33D	5		PB42D	5	
AL17	PB35A	5		PB43A	5	
AM17	PB35B	5		PB43B	5	
AE17	PB35C	5		PB43C	5	
AF17	PB35D	5		PB43D	5	
AM16	PB37A	4		PB45A	4	
AL16	PB37B	4		PB45B	4	
AF16	PB37C	4		PB45C	4	
AE16	PB37D	4		PB45D	4	
AM15	PB38A	4		PB46A	4	
AL15	PB38B	4		PB46B	4	
AD16	PB38C	4		PB46C	4	
AC16	PB38D	4		PB46D	4	
AM14	PB39A	4		PB47A	4	
AL14	PB39B	4		PB47B	4	
AG16	PB39C	4		PB47C	4	
AH16	PB39D	4		PB47D	4	
AK15	PB41A	4		PB49A	4	
AJ15	PB41B	4		PB49B	4	
AH15	PB41C	4		PB49C	4	
AH14	PB41D	4		PB49D	4	
AM13	PB42A	4		PB50A	4	
AM12	PB42B	4		PB50B	4	
AH13	PB42C	4		PB50C	4	
AH12	PB42D	4		PB50D	4	
AK14	PB43A	4		PB51A	4	
AJ14	PB43B	4		PB51B	4	
AE15	PB43C	4		PB51C	4	
AD15	PB43D	4		PB51D	4	
AL13	PB46A	4	PCLKT4_2	PB53A	4	PCLKT4_2
AL12	PB46B	4	PCLKC4_2	PB53B	4	PCLKC4_2
AG14	PB46C	4	PCLKT4_7	PB53C	4	PCLKT4_7
AG13	PB46D	4	PCLKC4_7	PB53D	4	PCLKC4_7
AM11	PB47A	4	PCLKT4_1	PB54A	4	PCLKT4_1
AM10	PB47B	4	PCLKC4_1	PB54B	4	PCLKC4_1

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
L33	PL27B	7		PL35B	7	
M30	PL27C	7		PL35C	7	
N30	PL27D	7		PL35D	7	
M31	PL29A	7		PL37A	7	
N31	PL29B	7		PL37B	7	
P24	PL29C	7		PL37C	7	
R24	PL29D	7		PL37D	7	
M33	PL30A	7		PL42A	7	
N33	PL30B	7		PL42B	7	
U25	PL30C	7		PL42C	7	
T25	PL30D	7		PL42D	7	
L34	PL31A	7		PL43A	7	
M34	PL31B	7		PL43B	7	
P29	PL31C	7		PL43C	7	
R29	PL31D	7		PL43D	7	
N34	PL34A	7		PL46A	7	
P34	PL34B	7		PL46B	7	
R27	PL34C	7		PL46C	7	
T27	PL34D	7		PL46D	7	
R32	PL35A	7	PCLKT7_1	PL47A	7	PCLKT7_1
R31	PL35B	7	PCLKC7_1	PL47B	7	PCLKC7_1
U24	PL35C	7	PCLKT7_3	PL47C	7	PCLKT7_3
T24	PL35D	7	PCLKC7_3	PL47D	7	PCLKC7_3
P33	PL36A	7	PCLKT7_0	PL48A	7	PCLKT7_0
R33	PL36B	7	PCLKC7_0	PL48B	7	PCLKC7_0
T26	PL36C	7	PCLKT7_2	PL48C	7	PCLKT7_2
U26	PL36D	7	PCLKC7_2	PL48D	7	PCLKC7_2
T32	PL38A	6	PCLKT6_0	PL50A	6	PCLKT6_0
T31	PL38B	6	PCLKC6_0	PL50B	6	PCLKC6_0
U29	PL38C	6	PCLKT6_1	PL50C	6	PCLKT6_1
V29	PL38D	6	PCLKC6_1	PL50D	6	PCLKC6_1
T30	PL39A	6		PL51A	6	
U30	PL39B	6		PL51B	6	
U27	PL39C	6	PCLKT6_3	PL51C	6	PCLKT6_3
V27	PL39D	6	PCLKC6_3	PL51D	6	PCLKC6_3
R34	PL40A	6		PL52A	6	
T34	PL40B	6		PL52B	6	
U28	PL40C	6	PCLKT6_2	PL52C	6	PCLKT6_2
V28	PL40D	6	PCLKC6_2	PL52D	6	PCLKC6_2
V30	PL43A	6		PL55A	6	
W30	PL43B	6		PL55B	6	
W27	PL43C	6	VREF1_6	PL55C	6	VREF1_6
Y27	PL43D	6		PL55D	6	
T33	PL44A	6		PL56A	6	
U33	PL44B	6		PL56B	6	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AN33	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AH29	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AJ29	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AM32	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AM31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AG27	PB4C	5	
AG26	PB4D	5	
AL29	PB5A	5	
AL28	PB5B	5	
AH27	PB5C	5	
AH26	PB5D	5	VREF1_5
AN32	PB7A	5	
AP32	PB7B	5	
AF25	PB7C	5	
AE25	PB7D	5	
AN31	PB11A	5	
AN30	PB11B	5	
AK29	PB11C	5	
AK28	PB11D	5	
AP31	PB12A	5	
AP30	PB12B	5	
AD24	PB12C	5	
AE24	PB12D	5	
AM29	PB15A	5	
AM28	PB15B	5	
AJ27	PB15C	5	
AJ26	PB15D	5	
AP29	PB16A	5	
AP28	PB16B	5	
AK27	PB16C	5	
AK26	PB16D	5	
AN29	PB19A	5	
AN28	PB19B	5	
AG25	PB19C	5	
AG24	PB19D	5	
AL26	PB20A	5	
AL25	PB20B	5	
AG23	PB20C	5	
AG22	PB20D	5	
AN27	PB23A	5	
AN26	PB23B	5	
AF24	PB23C	5	
AF23	PB23D	5	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
V8	PR65D	3	PCLKC3_3
U8	PR65C	3	PCLKT3_3
U5	PR65B	3	
T5	PR65A	3	
V6	PR64D	3	PCLKC3_1
U6	PR64C	3	PCLKT3_1
T4	PR64B	3	PCLKC3_0
T3	PR64A	3	PCLKT3_0
U9	PR62D	2	PCLKC2_2
T9	PR62C	2	PCLKT2_2
R2	PR62B	2	PCLKC2_0
P2	PR62A	2	PCLKT2_0
T11	PR61D	2	PCLKC2_3
U11	PR61C	2	PCLKT2_3
R4	PR61B	2	PCLKC2_1
R3	PR61A	2	PCLKT2_1
T8	PR60D	2	
R8	PR60C	2	
P1	PR60B	2	
N1	PR60A	2	
R6	PR57D	2	
P6	PR57C	2	
M1	PR57B	2	
L1	PR57A	2	
T10	PR56D	2	
U10	PR56C	2	
N2	PR56B	2	
M2	PR56A	2	
R11	PR51D	2	
P11	PR51C	2	
N4	PR51B	2	
M4	PR51A	2	
N5	PR49D	2	
M5	PR49C	2	
L2	PR49B	2	
K2	PR49A	2	
P8	PR47D	2	
N8	PR47C	2	
J2	PR47B	2	
H2	PR47A	2	
M6	PR45D	2	
L6	PR45C	2	
K3	PR45B	2	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
J3	PR45A	2	
M8	PR43D	2	DIFFR_2
L8	PR43C	2	VREF1_2
K4	PR43B	2	
J4	PR43A	2	
M7	PR26D	2	
L7	PR26C	2	
J5	PR26B	2	
H5	PR26A	2	
N9	PR19D	2	
P9	PR19C	2	
G3	PR19B	2	
F3	PR19A	2	
J6	PR18D	2	VREF2_2
H6	PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR15D	2	
H7	PR15C	2	
G5	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
C2	VCCJ	-	
M9	TDO	-	TDO
L9	TMS	-	
D1	TCK	-	
C1	TDI	-	
J8	PROGRAMN	1	
K8	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
B2	CCLK	1	
H9	RESP_URC	-	
H10	VCC12	-	
H8	A_REFCLKN_R	-	
G8	A_REFCLKP_R	-	
C3	VCC12	-	
D3	A_VDDIB0_R	-	
A3	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B3	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E5	VCC12	-	
A4	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
R12	VTT_2	2	
T12	VTT_2	2	
AB11	VTT_3	3	
W12	VTT_3	3	
Y12	VTT_3	3	
AC15	VTT_4	4	
AC16	VTT_4	4	
AD13	VTT_4	4	
AC19	VTT_5	5	
AC20	VTT_5	5	
AD22	VTT_5	5	
AB24	VTT_6	6	
W23	VTT_6	6	
Y23	VTT_6	6	
N24	VTT_7	7	
R23	VTT_7	7	
T23	VTT_7	7	
M12	VDDAX25_R	-	
M23	VDDAX25_L	-	
Y16	GND	-	
Y14	GND	-	
N21	VCC12	-	
P22	VCC12	-	
AA22	VCC12	-	
AB21	VCC12	-	
AB14	VCC12	-	
AA13	VCC12	-	
P13	VCC12	-	
N14	VCC12	-	
G26	NC	-	
G9	NC	-	
J12	NC	-	
H12	NC	-	
H23	NC	-	
J23	NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).
2. The LatticeSC/M115 in an 1152-pin package supports a 32-bit MPI interface.

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AU9	PB103C	4		PB117C	4	
AU8	PB103D	4		PB117D	4	
AY8	PB104A	4		PB118A	4	
AY7	PB104B	4		PB118B	4	
AU7	PB104C	4		PB118C	4	
AU6	PB104D	4		PB118D	4	
BA7	PB105A	4		PB119A	4	
BA6	PB105B	4		PB119B	4	
AN13	PB105C	4		PB119C	4	
AN12	PB105D	4		PB119D	4	
AV9	PB107A	4		PB121A	4	
AV8	PB107B	4		PB121B	4	
AT10	PB107C	4		PB121C	4	
AT9	PB107D	4		PB121D	4	
AW8	PB108A	4		PB122A	4	
AW7	PB108B	4		PB122B	4	
AP11	PB108C	4		PB122C	4	
AP10	PB108D	4		PB122D	4	
BB5	PB109A	4		PB123A	4	
BB4	PB109B	4		PB123B	4	
AR10	PB109C	4		PB123C	4	
AR9	PB109D	4		PB123D	4	
BA5	PB111A	4		PB125A	4	
BA4	PB111B	4		PB125B	4	
AT7	PB111C	4		PB125C	4	
AT6	PB111D	4		PB125D	4	
BB3	PB112A	4		PB126A	4	
BA3	PB112B	4		PB126B	4	
AM14	PB112C	4		PB126C	4	
AL14	PB112D	4		PB126D	4	
AY5	PB113A	4		PB127A	4	
AY4	PB113B	4		PB127B	4	
AN11	PB113C	4		PB127C	4	
AN10	PB113D	4		PB127D	4	
AV7	PB115A	4		PB129A	4	
AV6	PB115B	4		PB129B	4	
AM12	PB115C	4		PB129C	4	
AM11	PB115D	4		PB129D	4	
AW5	PB116A	4		PB130A	4	
AW4	PB116B	4		PB130B	4	
AT5	PB116C	4		PB130C	4	
AT4	PB116D	4		PB130D	4	
AY2	PB117A	4		PB131A	4	
BA2	PB117B	4		PB131B	4	
AP9	PB117C	4		PB131C	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V8	PR41C	2		PR55C	2	
T4	PR41B	2		PR55B	2	
U4	PR41A	2		PR55A	2	
V9	PR39D	2		PR53D	2	
U9	PR39C	2		PR53C	2	
V6	PR39B	2		PR53B	2	
U6	PR39A	2		PR53A	2	
AA12	PR38D	2		PR52D	2	
Y12	PR38C	2		PR52C	2	
P1	PR38B	2		PR52B	2	
N1	PR38A	2		PR52A	2	
T7	PR37D	2		PR51D	2	
R7	PR37C	2		PR51C	2	
T5	PR37B	2		PR51B	2	
R5	PR37A	2		PR51A	2	
U10	PR35D	2		PR49D	2	
V10	PR35C	2		PR49C	2	
P2	PR35B	2		PR49B	2	
N2	PR35A	2		PR49A	2	
T8	PR34D	2		PR48D	2	
R8	PR34C	2		PR48C	2	
N3	PR34B	2		PR48B	2	
P3	PR34A	2		PR48A	2	
M6	PR33D	2		PR47D	2	
M7	PR33C	2		PR47C	2	
T6	PR33B	2		PR47B	2	
R6	PR33A	2		PR47A	2	
V11	PR31D	2		PR45D	2	
U11	PR31C	2		PR45C	2	
M1	PR31B	2		PR45B	2	
L1	PR31A	2		PR45A	2	
Y14	PR30D	2		PR44D	2	
W14	PR30C	2		PR44C	2	
M2	PR30B	2		PR44B	2	
L2	PR30A	2		PR44A	2	
T9	PR29D	2	DIFFR_2	PR43D	2	DIFFR_2
R9	PR29C	2	VREF1_2	PR43C	2	VREF1_2
P4	PR29B	2		PR43B	2	
N4	PR29A	2		PR43A	2	
N7	PR26D	2		PR40D	2	
N8	PR26C	2		PR40C	2	
P5	PR26B	2		PR40B	2	
N5	PR26A	2		PR40A	2	
K7	PR25D	2		PR38D	2	
J7	PR25C	2		PR38C	2	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB25	VCC	-		VCC	-	
AB26	VCC	-		VCC	-	
AC16	VCC	-		VCC	-	
AC18	VCC	-		VCC	-	
AC20	VCC	-		VCC	-	
AC23	VCC	-		VCC	-	
AC25	VCC	-		VCC	-	
AC27	VCC	-		VCC	-	
AD17	VCC	-		VCC	-	
AD19	VCC	-		VCC	-	
AD21	VCC	-		VCC	-	
AD22	VCC	-		VCC	-	
AD24	VCC	-		VCC	-	
AD26	VCC	-		VCC	-	
AE16	VCC	-		VCC	-	
AE18	VCC	-		VCC	-	
AE20	VCC	-		VCC	-	
AE21	VCC	-		VCC	-	
AE22	VCC	-		VCC	-	
AE23	VCC	-		VCC	-	
AE25	VCC	-		VCC	-	
AE27	VCC	-		VCC	-	
AF17	VCC	-		VCC	-	
AF19	VCC	-		VCC	-	
AF21	VCC	-		VCC	-	
AF22	VCC	-		VCC	-	
AF24	VCC	-		VCC	-	
AF26	VCC	-		VCC	-	
AG18	VCC	-		VCC	-	
AG20	VCC	-		VCC	-	
AG23	VCC	-		VCC	-	
AG25	VCC	-		VCC	-	
T18	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
T23	VCC	-		VCC	-	
T25	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
U22	VCC	-		VCC	-	
U24	VCC	-		VCC	-	
U26	VCC	-		VCC	-	
V16	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-6FCN1152I[2]	-6	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FCN1152I[2]	-5	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSC3GA80E-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.